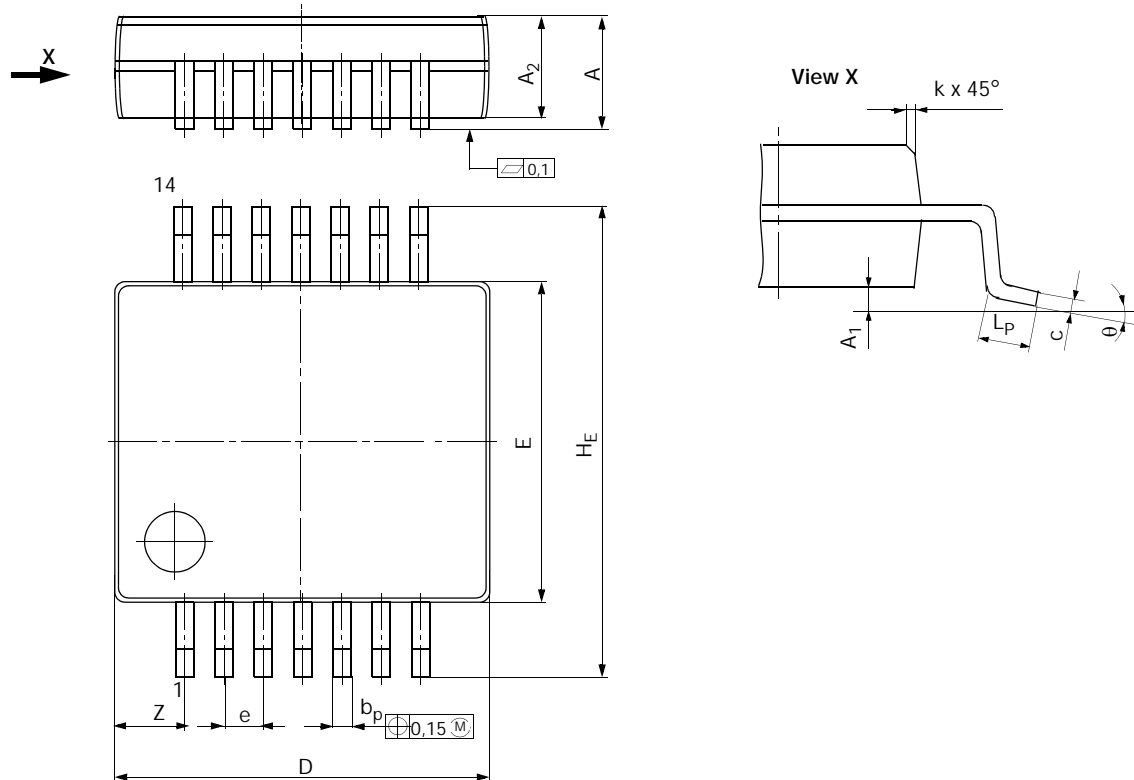
	<b>Package SSOP14</b> (5,3 mm)	<b>MDS</b> <b>761</b>
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Dimensions in millimetres

Based on JEDEC JEP95: MO-150

**1 Dimensions**

Dimensions of Sub-Group B1	
$A_{max}$	1,99
$b_{Pmin}$	0,25
$b_{Pmax}$	0,38
$e_{nom}$	0,65
$H_{Emin}$	7,65
$H_{Emax}$	7,90
$L_{Pmin}$	0,63
$Z_{max}$	1,22

Dimensions of Sub-Group C1	
$A_{min}$	1,73
$A_{1min}$	0,05
$A_{1max}$	0,21
$A_{2min}$	1,68
$A_{2max}$	1,78
$c_{min}$	0,09
$c_{max}$	0,20
$D_{min}^*$	6,07
$D_{max}^*$	6,33
$E_{min}^*$	5,20
$E_{max}^*$	5,38
$k_{min}$	0,25
$\theta_{min}$	0°
$\theta_{max}$	10°

- 2 Weight**  $\leq 0,3$  g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

\* without mold-flash

Zentrum Mikroelektronik Dresden		
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